

Appendix A

LEAD FINISH

Axial devices are Tin/Lead Plated in accordance with MIL-PRF-19500 Appendix H

HI-REL SCREENING

Screened in accordance with MIL-PRF-19500 JANTX level, Appendix E, Table IV.

CHIPS

Standard metallization for chips: Aluminum Anode/Silver Cathode.
100% visual Inspection in accordance with MIL-STD-750 Method 2073

STANDARD PACKAGING

CHIPS

ESD Waffle Pack

SOT-23/SOD-323

Waffle Pack (Quantities <500)
Tape & Reel (3,000/7" reel)

SOD-523

Tape & Reel (6,000/7" reel)

SOT-223

Waffle Pack (Quantities <500)
Tape & Reel (1,000/7" reel)

TO-92

Bulk (0.1" Lead Spacing 1,000/Bag)
Fan Fold not available

DO-7

Bulk (1,000/bag or 300/ jar-polarized * ESD packaging not available in jars)
Unit Packaging (flat packs 50/pack-polarized or single unit pack)
Tape & Reel (2,000/10" reel; 6,000/14" reel)
Ammo Pack (less than 100 pieces)